



NOTES:

1. MATERIALS:

HOUSING: HIGH TEMP. THERMOPLASTIC, BLACK, UL 94V-0
 CONTACTS: 0.014 INCHES (0.35 MINIMETERS) THICK PHOSPHOR BRONZE PLATED WITH 150 MICROINCHES (3.81 MICROMETERS) MINIMUM THICK TIN LEAD IN SOLDER AREA. 50 MICROINCHES (1.27 MICROMETERS) MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE CONTACTS PLATED WITH 50 MICROINCHES (1.27 MICROMETERS) MINIMUM THICK NICKEL.

SHIELDED: 0.0098 INCHES (0.25 MINIMETERS) THICK COPPER ZINC ALLOY PLATED WITH 30 MICROINCHES (0.762 MICROMETERS) MINIMUM THICK NICKEL

2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F

3. UNSPECIFIED TOLERANCE: .XX ±0.25[0.010]
 .X ±0.30[0.012]

RoHS Compliant

X MULTIPLE			CONNECTING THE INFORMATION AGE
X MULTIPLE ASIA 4F, No. 347, Yang Guang St., Neihu Chiu, Taipei, Taiwan 11475	X MULTIPLE USA 543 Country Club Drive #B 128 Simi Valley, CA 93065	G/NO:	
THIS DRAWING IS A CONTROLLED DOCUMENT.			
TITLE: Stacked RJ45 Connectors, w/LED, 8P, 8C, Shielded, Thru Hole		DWG NO: XRJDB-S-01-8-8-1-MT50	
PART NO: XRJDB-S-01-8-8-1-MT50		DRAWN: RUNES	
UNIT mm[inch]		SHEET 1 of 1	REV B
DATE: Jan.11.06		CHKD: JEFF	